

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) Process for gluing at least one micro-structured substrate comprising upper coplanar plane areas and recesses between them, by means of a glue that can bond to these upper coplanar plane areas, this process being characterised in that it comprises the following steps:

-a mask-less grid is placed above the substrate,

-this grid is coated with glue using a tool which presses on the grid and locally brings this grid into contact with the upper coplanar plane areas, so as to deposit a film of glue droplets on these upper coplanar plane area without said film entering into said recesses, and

-the grid is removed,

process in which the upper coplanar plane areas are treated before the film of glue droplets is deposited on it, this treatment being designed to adapt the wettability of these areas to the glue.

2. (Original) Process according to claim 1, in which the tool is a doctor blade.

3. (Original) Process according to claim 1, in which this treatment is designed to control spreading of glue droplets on the upper coplanar plane areas.

4. (Original) Process according to claim 1, in which the micro-structured substrate is closed with a closing substrate that is fixed to the upper coplanar plane areas by the glue deposited on them.

5. (Original) Process according to claim 4, in which recesses in the micro-structured substrate comprise areas which are provided with biological probes.
6. (Original) Process according to claim 4, in which the closing substrate comprises areas provided with biological probes, these areas being designed to be positioned facing the recesses in the micro-structured substrate after this micro-structured substrate has been closed.
7. (Original) Process according to claim 4, in which the closing substrate comprises drillings through which a fluid will be added into the recesses in the micro-structured substrate.
8. (Previously Presented) Process according to claim 4, in which a set of micro-structured substrates are collectively fabricated in advance on the same substrate, the upper plane areas of all the micro-structured substrates being coplanar, the film of glue droplets is deposited collectively on all of these upper plane areas, all of the micro-structured substrates are closed by the same closing substrate and the micro-structured substrates thus closed are separated from each other.
9. (Previously Presented) Process according to claim 4, in which a set of micro-structured substrates are collectively fabricated in advance on the same substrate, the upper plane areas of all the micro-structured substrates being coplanar, and a set of closing substrates is fabricated collectively on another substrate, also in advance, the micro-structured substrates and the closing substrates are separated from each other and the micro-structured substrates are closed by the closing substrates after depositing the film of glue droplets on the upper coplanar plane areas of each micro-structured substrate.

10. (Previously Presented) Process according to claim 4, in which each substrate is made from a material chosen from among one or more of glass, silicon or polymers.
11. (Previously Presented) Process according to claim 1, in which at least one recess has a width dimension equal to or less than 100 μm .
12. (Currently Amended) Process according to claim 1, in which the mask-less grid prevents glue from entering at least one of the recesses due to a predetermined difference between a first surface tension force of the mask-less grid and a second tension force of the upper coplanar plane areas.
13. (Currently Amended) A method for gluing at least one micro-structured substrate having an upper coplanar plane area and a recess adjacent to the upper coplanar plane area, the method comprising:
 - increasing wettability of the upper coplanar plane area to accept glue thereon, wherein the upper coplanar plane includes a first surface tension force associated therewith;
 - placing a mask-less grid above the substrate, wherein the mask-less grid has a second surface tension force associated therewith;
 - pressing the grid locally into contact with the upper coplanar plane;
 - depositing a film of glue on the upper coplanar area through the grid while in contact with the upper coplanar plane, wherein the glue only transfers from the grid to the upper coplanar plane due to a predetermined difference in the surface tension forces; and
 - removing the grid away from and out of contact with the upper coplanar plane areas, wherein the glue does not enter the recess.

14. (Previously Presented) Method according to claim 13, in which at least one recess has a width dimension equal to or less than 100 μm .

15. (Currently Cancelled)